



Product Change Notification / JAON-07MXUP507

Date:

05-Aug-2022

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4810 Final Notice: Qualification of ATP7 as an additional assembly site for selected Atmel ATXMEGA128A4U, ATXMEGA128D4 and ATXMEGA64D4 device families available in 44L VQFN (7x7x1.0mm) package.

Affected CPNs:

[JAON-07MXUP507_Affected_CPN_08052022.pdf](#)
[JAON-07MXUP507_Affected_CPN_08052022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of ATP7 as an additional assembly site for selected Atmel ATXMEGA128A4U, ATXMEGA128D4 and ATXMEGA64D4 device families available in 44L VQFN (7x7x1.0mm) package.

Pre and Post Change Summary:

| | | Pre Change | Post Change | |
|---------------------------|------------------|---|---|--------------|
| Assembly Site | ASE Inc. (ASE) | ASE Inc. (ASE) | Amkor Technology Philippines (P3/P4), INC. (ATP7) | |
| Wire Material | PdCu | PdCu | CuPdAu | |
| Die Attach Material | CRM-1076WA | CRM-1076WA | CRM1085A | |
| Molding Compound Material | G631H | G631H | G631BQF | |
| Lead frame | Material | C194 | C194 | C194FH |
| | Paddle size | 213X213 mils | 213X213 mils | 217X217 mils |
| | DAP Surface Prep | Spot Plating | Spot Plating | PPF |
| | | See pre and post change attachment for lead frame comparison. | | |

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change: To improve productivity and on-time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date:September 1, 2022 (date code: 2236)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

| | | | | | | | | | | | |
|-------------------------------|--|--|--|--|--|--|--|--|---|--|--|
| Date | | | | | | | | | | | |
| Estimated Implementation Date | | | | | | | | | X | | |

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:September 13, 2021: Issued initial notification.

August 5, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on September 1, 2022. Updated post lead frame material from C194 to C194FH. Updated post lead frame DAP Surface Prep from ring plating to PPF.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-07MXUP507_Pre and Post Change Summary.pdf](#)
[PCN_JAON-07MXUP507_Qual_Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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